

**M.TECH/VLSI/2ND SEM/VLSI 5202/2015
2015**

**VLSI Design, Verification and Testing
(VLSI 5202)**

Time Allotted : 3 hrs

Full Marks : 70

Figures out of the right margin indicate full marks.

***Candidates are required to answer Group A and
any 5 (five) from Group B to E, taking at least one from each group.***

***Candidates are required to give answer in their own words as far as
practicable.***

Group - A

(Multiple Choice Type Questions)

1. Choose the correct alternative for the following: **10 x 1=10**
- (i) In which of the following Memory array Periodic Refresh is needed?
(a) ROM (b) Register File (c) DRAM (d) SRAM.
- (ii) Which memory can hold the bit value when there is no power supply?
(a) SRAM (b) ROM (c) DRAM (d) Register File.
- (iii) Memory with multiple read and write port is
(a) SRAM (b) ROM (c) Register File (d) DRAM.
- (iv) For modern process, Wire Aspect Ratio (t/w) is
(a) 1 (b) 2 (c) 3 (d) 4.
- (v) Wire RC model acts as
(a) Low pass filter (b) High pass filter
(c) Band pass filter (d) All pass filter.
- (vi) Transistor performs slowest at
(a) High Voltage, High Temperature (b) High Voltage, Low Temperature
(c) Low Voltage, High Temperature (d) Low Voltage, Low Temperature.
- (vii) ATPG is based on
(a) Stuck at fault (b) DFT (c) Bridging fault (d) BIST.
- (viii) Signature analyser (SA) is part of
(a) Scan Design (b) Boundary Scan (c) BIST (d) Ad hoc DFT.
- (ix) Hold margin for a path is +20ps for Cycle Time of 200ps. If Cycle time is reduced to 180ps, then new hold margin for the path will be
(a) +40ps (b) +20ps (c) 0ps (d) -20ps.
- (x) Yield $Y = 99\%$ and Fault Coverage $T = 90\%$, DPM (Defects Per Million) is
(a) 1000 (b) 10,000 (c) 28,000 (d) 50,000.

Group - B

- 2.(a) Explain various components of a Memory Block with Diagram.
- (b) For a Memory Block of 4K Memory Locations and 16 Data bits, Explain how many row address bits and how many column address bits are needed.
- 6+6=12**
- 3.(a) Explain write '1' followed by read '1' operation in 1-Transistor DRAM Circuit using circuit diagram and timing waveforms.
- (b) Explain sizing criteria of 6 Transistor SRAM cell.
- 6+6=12**

Group - C

- 4.(a) Explain difference between differential Pair Sense Amplifier vs Latch based Sense Amplifier with circuit diagram
- (b) What is best circuit scheme to create 5 to 32 bit decoder? Explain with diagram.
- 6+6=12**
- 5.(a) As per Process Technology, Metal-8 resistance is 100mohms/um and capacitance is 0.2ff/um. If 1mm wire is routed using Metal-8, draw circuit diagram of 3 segment pi model with appropriate resistance and capacitance value of individual segments.
- (b) Why driver side of a wire needs to be low resistance and receiver side of the wire needs to be low capacitance, explain using Elmore Delay model?
- 6+6=12**

Group - D

- 6.(a) For a flip flop based sequential circuit, Cycle Time = 200ps, Setup Time = 30ps, Clock-Skew = 20ps, Combinational Delay = 60ps, Clock to Out Delay of Flop = 40ps. Hold Time = 50ps. What is setup margin and hold margin for the Circuit?
- (b) What is clock skew and what are sources of Clock Skew?
- 6+6=12**
- 7.(a) Explain H-Tree of clock distribution using circuit diagram.
- (b) Explain transparency of a D-Latch with circuit diagram and timing waveforms.
- 6+6=12**

Group - E

8.(a) What is input test pattern to detect Stuck-at-1 fault at the Output of a 2 input NAND gate ?

(b) Explain D-Algorithm using an example.

6+6=12

9.(a) Draw Circuit diagram of Scan Flip Flop and explain how it works.

(b) Draw block diagram of Scan Design/Structure and explain its operation.

6+6=12